

DOUBLE SIDED SINGLE INLINE MEMORY MODULE

ABSTRACT OF THE DISCLOSURE

A double sided single inline memory module (20) comprising a substrate (70) having a plurality of openings (86) and first and second surfaces (92, 94), a plurality of pads (82) being integral with the substrate (70) and extending into the opening (86), a plurality of chips (50) adhered to the substrate (70) having bonding pads (120), wire bonding (80) electrically connecting at least one of the bonding pads (120) to at least one of the pads (82) and potting material (90) encapsulating the wire bonding (80) and filling the opening (86) is disclosed.

FIGURE 1